

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) ~~An underlayer-A resist underlayer~~ coating forming composition used in a lithography process of manufacture of a semiconductor device ~~characterized by~~ comprising a polymer compound having an epoxy group and a polymer compound having a phenolic hydroxyl group, a carboxyl group, a protected carboxyl group or an acid anhydride-~~structure.~~ structure, at least one of both polymer compounds having a triazine skeleton.

2. (Currently Amended) ~~An underlayer-A resist underlayer~~ coating forming composition used in a lithography process of manufacture of a semiconductor device ~~characterized by~~ comprising a polymer compound having an epoxy group and a compound with a molecular weight of 2000 or less having at least two phenolic hydroxyl groups, carboxyl groups, protected carboxyl groups or acid anhydride-~~structures.~~ structures, at least one of the polymer compound and the compound having a triazine skeleton.

3. (Currently Amended) ~~An underlayer-A resist underlayer~~ coating forming composition used in a lithography process of manufacture of a semiconductor device ~~characterized by~~ comprising a compound with a molecular weight of 2000 or less having at least two epoxy groups and a polymer compound having a phenolic hydroxyl group, a carboxyl group, a protected carboxyl group or an acid anhydride-~~structure.~~ structure, at least one of the compound and the polymer compounds having a triazine skeleton.

4. (Currently Amended) ~~An underlayer-A resist underlayer~~ coating forming composition used in a lithography process of manufacture of a semiconductor device ~~characterized by~~ comprising a polymer compound having a phenolic hydroxyl group, a

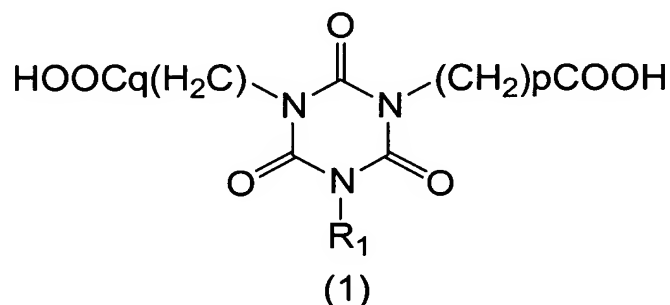
carboxyl group, a protected carboxyl group or an acid anhydride ~~structure and structure~~, an epoxy ~~group~~ group, and a triazine skeleton.

5. (Original) The underlayer coating forming composition according to claim 1 or 3, wherein the polymer compound having a carboxyl group is a compound having acrylic acid or methacrylic acid as a unit structure.

6. (Original) The underlayer coating forming composition according to claim 1 or 3, wherein the polymer compound having a phenolic hydroxyl group is a compound having hydroxystyrene as a unit structure.

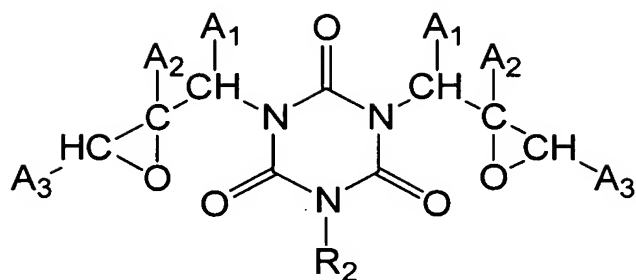
7. (Original) The underlayer coating forming composition according to claim 3, wherein the compound with a molecular weight of 2000 or less having at least two epoxy groups is a compound having at least three epoxy groups and no aromatic ring structure.

8. (Original) The underlayer coating forming composition according to claim 2, wherein the compound with a molecular weight of 2000 or less having at least two carboxyl groups is a compound of formula (1)



wherein p and q is a number of 1 to 6, R₁ is hydrogen atom, C₁₋₆ alkyl group, C₃₋₆ alkenyl group, benzyl group, phenyl group or -(CH₂)_rCOOH wherein r is a number of 1 to 6.

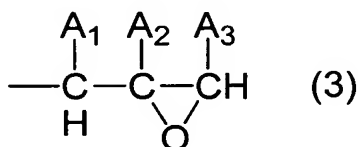
9. (Original) The underlayer coating forming composition according to claim 3, wherein the compound with a molecular weight of 2000 or less having at least two epoxy groups is a compound of formula (2)



(2)

wherein A₁, A₂ and A₃ each are hydrogen atom, methyl group or ethyl group, R₂ is hydrogen atom, C₁₋₆ alkyl group, C₃₋₆ alkenyl group, benzyl group, phenyl group or a group of formula

(3)



(3)

10. (Original) The underlayer coating forming composition according to claim 2, wherein the compound with a molecular weight of 2000 or less having at least two phenolic hydroxyl groups is at least one compound selected from the group consisting of a hydroxystyrene oligomer, a substituted bi-phenol compound, a substituted tris-phenol compound, a methylolated phenol compound, a methylolated bisphenol compound, a substituted phenol novolak and a substituted cresol novolak.

11. (Previously Presented) The underlayer coating forming composition according to claim 1, further comprising a light absorbing compound.

12. (Previously Presented) A method for forming an underlayer coating for use in manufacture of semiconductor device, comprising coating the underlayer coating forming composition according to claim 1.

13. (Previously Presented) A method for forming photoresist pattern for use in manufacture of semiconductor device, comprising

coating the underlayer forming composition according to claim 1 on a semiconductor substrate, and baking it to form an underlayer coating, forming a photoresist layer on the underlayer coating, exposing the semiconductor substrate covered with the underlayer coating and the photoresist layer to light, and developing the photoresist layer after the exposure to light.

14. (Original) The method for forming photoresist pattern according to claim 13, wherein the exposure to light is carried out with a light of a wavelength of 248 nm, 193 nm or 157 nm.